

MICRO SIM CARD

NOTES:

MATERIAL:

Insulator: High Temperature Thermoplastic,UL 94V-0.
Contact: Copper Alloy
Shell: STAINLESS

PLATING:

Contact: Plated 30u' Ni Overall Contact Au 1U
Shell: Plated 30u' Ni Overall
Plated 1u'Au Selective Contact Area

Electrical:

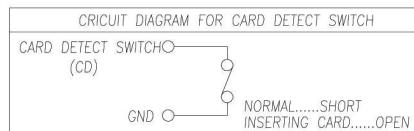
Current Rating :0.5mA AC/DC max.
Voltage Rating :125V AC/DC
Ambient Temperature Range :-20° C~+60° C
Storage Temperature Range :-40° C~+70° C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩmax.
Insulation Resistance:1000MΩmin./500VDC
Mating Cycles:10000 Insertions
Temperature: 260° C ±5°

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

■ CIRCUT TRACE KEEP OUT AREA
■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



TOLERANCE UNSPECIFIED	
X. ±0.30	.X' ±3°
.X ±0.25	.X' ±2°
.XX ±0.20	.XX' ±1°
.XXX ±0.05	.XXX' ±0.5°

深圳市金航标电子有限公司



DATE 2014/5/27

TITLE	MICRO SIM PUSH 6P
产品名称	
PART NUMBER	C3P206J2640
产品料号	
DRAWING NUMBER	
图纸编号	

UNIT	DESIGNED
单位 (mm)	设计 罗正富
SCALE	CHECKED
比例 1: 1	核准 罗利斌
SHEET	APPROVED
页码 1/1	审核 张华宇